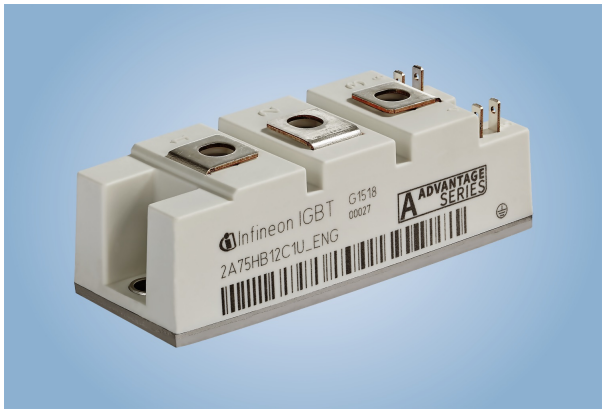
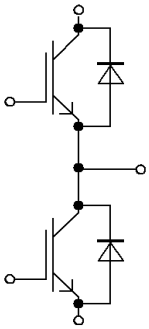
技术信息 / Technical Information

IGBT-模块
IGBT-Module

2A50HB12C1U

目标数据 / Target Data





V_{CES} = 1200V
$I_{C\ nom}$ = 50A / I_{CRM} = 100A

典型应用
- 工业焊机

Typical Applications
- Welding

电气特性
- 低开关损耗
- $T_{vj\ op}$ = 125°C
- 超快速IGBT芯片

Electrical Features
- Low Switching Losses
- $T_{vj\ op}$ = 125°C
- Ultra fast IGBT Chips

机械特性
- 铜基板
- 标准封装

Mechanical Features
- Copper Base Plate
- Standard Housing

Module Label Code

Barcode Code 128

Sample
00000123456000000000000

DMX - Code

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

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技术信息 / Technical Information

IGBT-模块
IGBT-Module

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ADVANTAGE SERIES

目标数据
Target Data

IGBT, 逆变器 / IGBT,Inverter

最大额定值 / Maximum Rated Values

集电极 - 发射极电压 Collector-emitter voltage	T_{vj} = 25°C	V_{CES}	1200		V
连续集电极直流电流 Continuous DC collector current	T_C = 70°C, $T_{vj\,max}$ = 125°C	$I_{C\,nom}$	50		A
集电极重复峰值电流 Repetitive peak collector current	t_P = 1 ms	I_{CRM}	100		A
总功率损耗 Total power dissipation	T_C = 25°C, $T_{vj\,max}$ = 125°C	P_{tot}	145		W
栅极 - 发射极峰值电压 Gate-emitter peak voltage		V_{GES}	+/-20		V

特征值 / Characteristic Values

			min.	typ.	max.	
集电极 - 发射极饱和电压 Collector-emitter saturation voltage	I_C = 50 A, V_{GE} = 15 V I_C = 50 A, V_{GE} = 15 V	T_{vj} = 25°C T_{vj} = 125°C	$V_{CE\,sat}$		2,05 2,50	2,40	V V
栅极阈值电压 Gate threshold voltage	I_C = 1,70 mA, V_{CE} = V_{GE}, T_{vj} = 25°C		V_{GEth}	5,25	5,80	6,25	V
栅极电荷 Gate charge	V_{GE} = -15 V ... +15 V		Q_G		0,23		µC
内部栅极电阻 Internal gate resistor	T_{vj} = 25°C		R_{Gint}		0,0		Ω
输入电容 Input capacitance	f = 1 MHz, T_{vj} = 25°C, V_{CE} = 25 V, V_{GE} = 0 V		C_{ies}		3,00		nF
反向传输电容 Reverse transfer capacitance	f = 1 MHz, T_{vj} = 25°C, V_{CE} = 25 V, V_{GE} = 0 V		C_{res}		0,16		nF
集电极-发射极截止电流 Collector-emitter cut-off current	V_{CE} = 1200 V, V_{GE} = 0 V, T_{vj} = 25°C		I_{CES}			1,0	mA
栅极-发射极漏电流 Gate-emitter leakage current	V_{CE} = 0 V, V_{GE} = 20 V, T_{vj} = 25°C		I_{GES}			100	nA
开通延迟时间(电感负载) Turn-on delay time, inductive load	I_C = 50 A, V_{CE} = 1200 V V_{GE} = ±15 V R_{Gon} = 15 Ω	T_{vj} = 25°C T_{vj} = 125°C	$t_{d\,on}$		0,21 0,24		µs µs
上升时间(电感负载) Rise time, inductive load	I_C = 50 A, V_{CE} = 1200 V V_{GE} = ±15 V R_{Gon} = 15 Ω	T_{vj} = 25°C T_{vj} = 125°C	t_r		0,05 0,06		µs µs
关断延迟时间(电感负载) Turn-off delay time, inductive load	I_C = 50 A, V_{CE} = 1200 V V_{GE} = ±15 V R_{Goff} = 15 Ω	T_{vj} = 25°C T_{vj} = 125°C	$t_{d\,off}$		0,39 0,45		µs µs
下降时间(电感负载) Fall time, inductive load	I_C = 50 A, V_{CE} = 1200 V V_{GE} = ±15 V R_{Goff} = 15 Ω	T_{vj} = 25°C T_{vj} = 125°C	t_f		0,02 0,045		µs µs
开通损耗能量 (每脉冲) Turn-on energy loss per pulse	I_C = 50 A, V_{CE} = 1200 V, L_S = 35 nH V_{GE} = ±15 V R_{Gon} = 15 Ω	T_{vj} = 25°C T_{vj} = 125°C	E_{on}		6,50 9,00		mJ mJ
关断损耗能量 (每脉冲) Turn-off energy loss per pulse	I_C = 50 A, V_{CE} = 1200 V, L_S = 35 nH V_{GE} = ±15 V R_{Goff} = 15 Ω	T_{vj} = 25°C T_{vj} = 125°C	E_{off}		1,90 2,80		mJ mJ
短路数据 SC data	V_{GE} ≤ 15 V, V_{CC} = 800 V V_{CEmax} = V_{CES} -L_{sCE} ·di/dt	t_P ≤ 10 µs, T_{vj} = 125°C	I_{SC}		150		A
结 - 外壳热阻 Thermal resistance, junction to case	每个 IGBT / per IGBT		R_{thJC}			0,700	K/W
外壳 - 散热器热阻 Thermal resistance, case to heatsink	每个 IGBT / per IGBT λ_{Paste} = 1 W/(m·K) / λ_{grease} = 1 W/(m·K)		R_{thCH}		0,0900		K/W
在开关状态下温度 Temperature under switching conditions			$T_{vj\,op}$	-40		125	°C

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目标数据
Target Data

二极管,逆变器 / Diode, Inverter

最大额定值 / Maximum Rated Values

反向重复峰值电压 Repetitive peak reverse voltage	T_{vj} = 25°C	V_{RRM}	1200	V
连续正向直流电流 Continuous DC forward current		I_F	25	A
正向重复峰值电流 Repetitive peak forward current	t_P = 1 ms	I_{FRM}	50	A
I2t-值 I²t - value	V_R = 0 V, t_P = 10 ms, T_{vj} = 125°C	I²t	140	A²s

特征值 / Characteristic Values

			min.	typ.	max.	
正向电压 Forward voltage	I_F = 25 A, V_{GE} = 0 V I_F = 25 A, V_{GE} = 0 V	V_F		1,70 1,70	2,15	V V
结 - 外壳热阻 Thermal resistance, junction to case	每个二极管 / per diode	R_{thJC}			1,60	K/W
外壳 - 散热器热阻 Thermal resistance, case to heatsink	每个二极管 / per diode λ_{Paste} = 1 W/(m·K) / λ_{grease} = 1 W/(m·K)	R_{thCH}		0,150		K/W
在开关状态下温度 Temperature under switching conditions		$T_{vj\,op}$	-40		125	°C

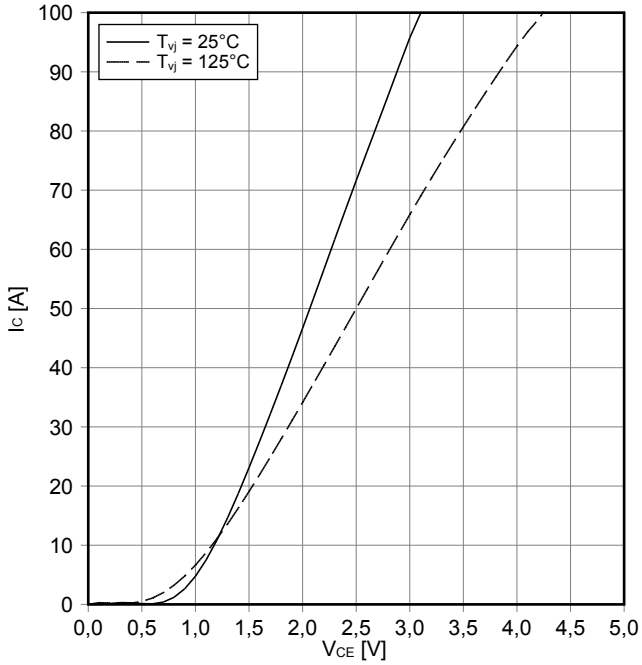
模块 / Module

绝缘测试电压 Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V_{ISOL}	2,5		kV
模块基板材料 Material of module baseplate			Cu		
内部绝缘 Internal isolation	基本绝缘 (class 1, IEC 61140) basic insulation (class 1, IEC 61140)		Al_2O_3		
爬电距离 Creepage distance	端子至散热器 / terminal to heatsink 端子至端子 / terminal to terminal		21,5 13,0		mm
电气间隙 Clearance	端子至散热器 / terminal to heatsink 端子至端子 / terminal to terminal		21,5 5,0		mm
相对电痕指数 Comperative tracking index		CTI	> 200		

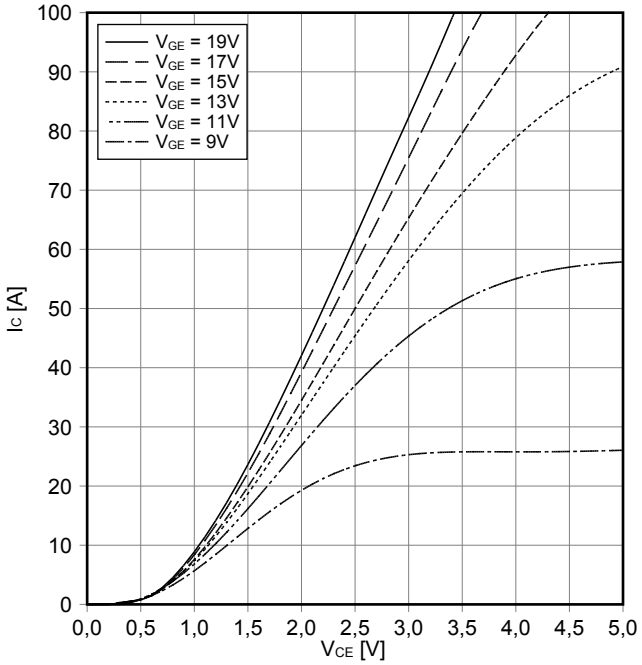
			min.	typ.	max.	
外壳 - 散热器热阻 Thermal resistance, case to heatsink	每个模块 / per module λ_{Paste} = 1 W/(m·K) / λ_{grease} = 1 W/(m·K)	R_{thCH}		0,05		K/W
杂散电感,模块 Stray inductance module		L_{sCE}		30		nH
储存温度 Storage temperature		T_{stg}	-40		125	°C
模块安装的安装扭距 Mounting torque for modul mounting	螺丝 M6 根据相应的应用手册进行安装 Screw M6 - Mounting according to valid application note	M	3,00		5,00	Nm
端子联接扭距 Terminal connection torque	螺丝 M5 根据相应的应用手册进行安装 Screw M5 - Mounting according to valid application note	M	2,5	-	5,0	Nm
重量 Weight		G		160		g

目标数据
Target Data

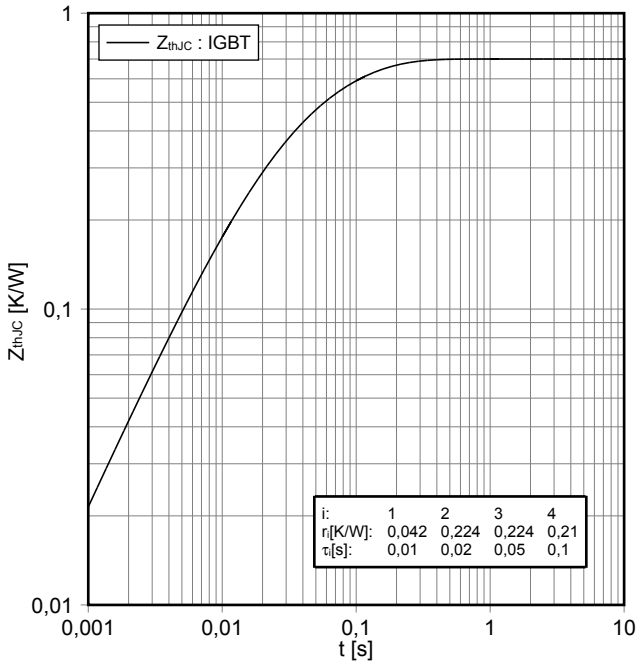
输出特性 IGBT, 逆变器 （典型)
output characteristic IGBT,Inverter (typical)
$I_C = f(V_{CE})$
V_{GE} = 15 V



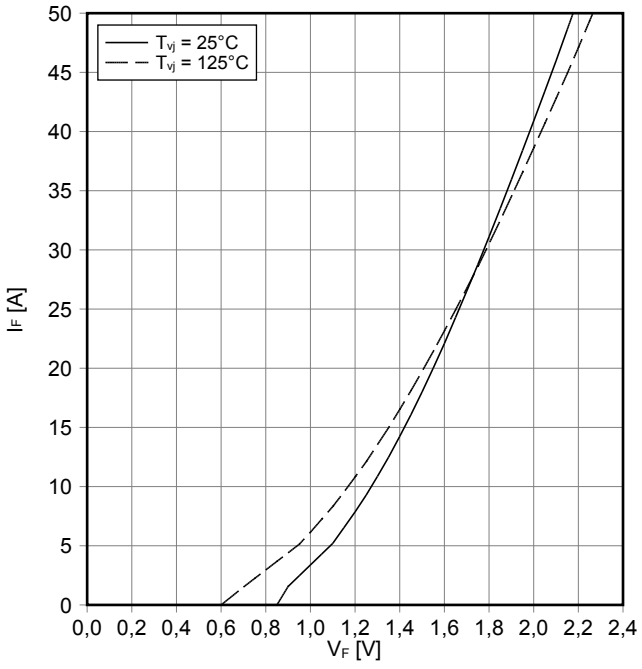
输出特性 IGBT, 逆变器 （典型)
output characteristic IGBT,Inverter (typical)
$I_C = f(V_{CE})$
T_{vj} = 125°C



瞬态热阻抗 IGBT, 逆变器
transient thermal impedance IGBT,Inverter
$Z_{thJC} = f(t)$



正向偏压特性 二极管,逆变器 （典型)
forward characteristic of Diode, Inverter (typical)
$I_F = f(V_F)$



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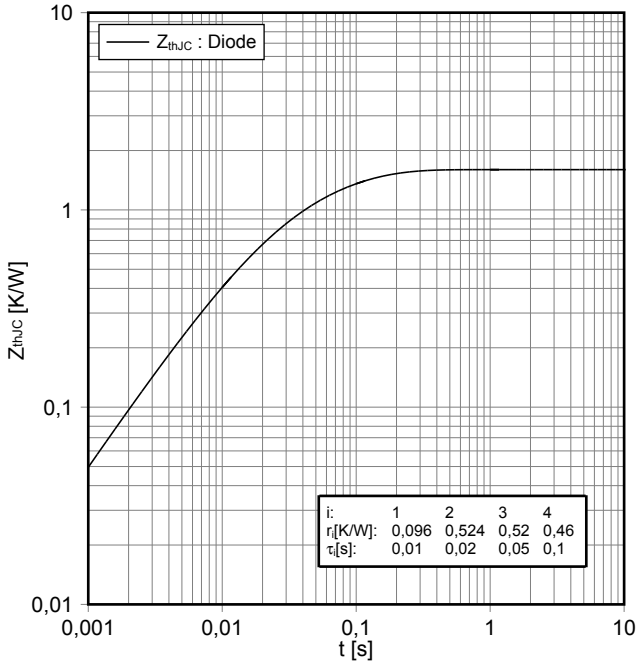
瞬态热阻抗 二极管,逆变器
transient thermal impedance Diode, Inverter
$Z_{thJC} = f(t)$



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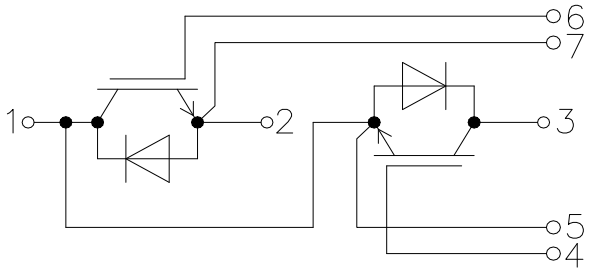
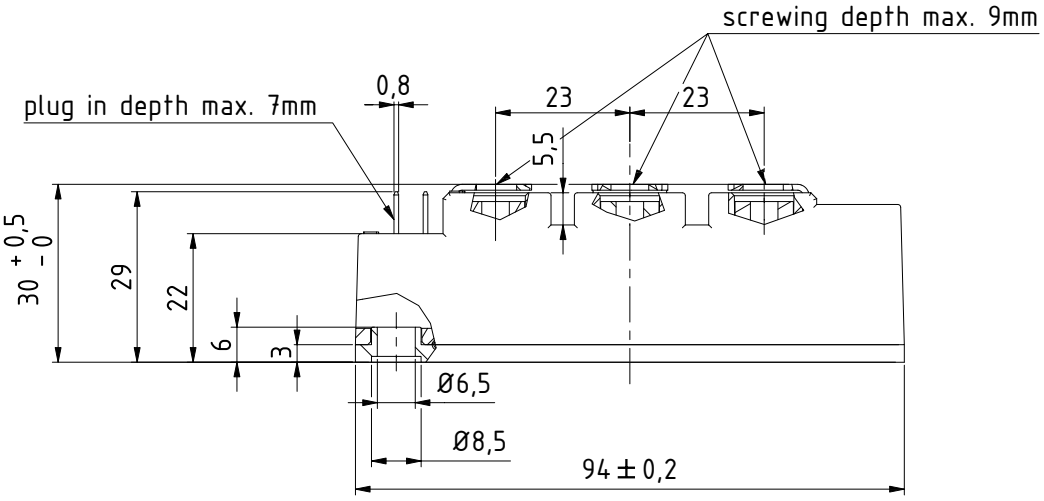
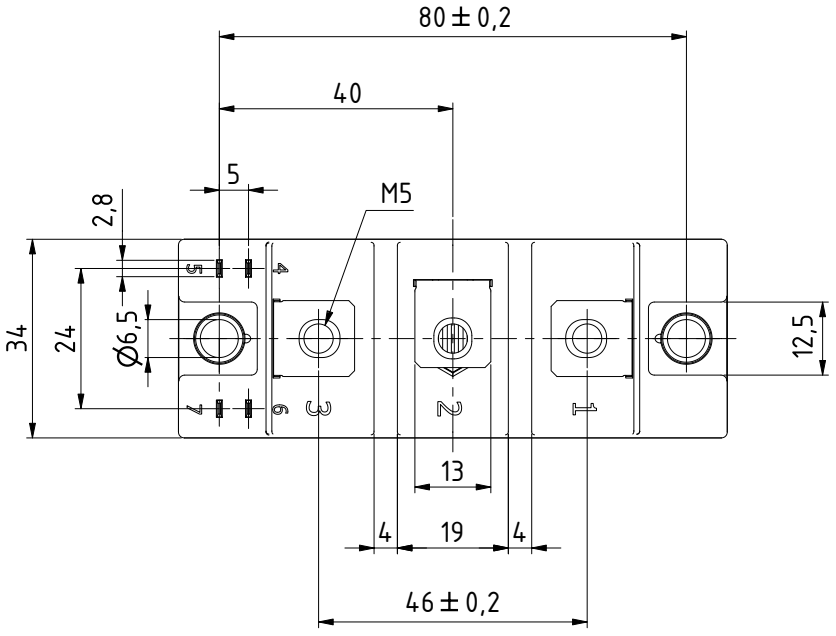
目标数据
Target Data

接线图 / Circuit diagram



封装尺寸 / Package outlines





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目标数据
Target Data

使用条件和条款

使用条件和条款
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-得到质量协议的结论
- 建立联合的测试和出厂产品检查， 我们可以根据测试的实际情况供货
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Should you intend to use the Product in aviation applications, in health or live endangering or life support applications, please notify. Please note, that for any such applications we urgently recommend
- to perform joint Risk and Quality Assessments;
- the conclusion of Quality Agreements;
- to establish joint measures of an ongoing product survey, and that we may make delivery depended on the realization of any such measures.

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